

# Amphenol

Mock-up attachment system for 3.2T Module – Part of the PLL Co-Packaging demo:  
This display helps visualize an overall system implementation with both Co-Packaged Optics (CPO) transceivers and copper cable attach (CCA) modules. The common footprint supports a socket interface for the Optical Module and a compatible direct-to-substrate connection for Copper Modules. The 16 total modules are arranged in close proximity to the switch ASIC.

Dual Compression Socket 3.2T Module – Part of the PLL Co-Packaging demo:  
The socket component holds 793 contacts in position to support all Optical Modules compliant with the 3.2T Module specification.

QSFP-DD800 Active Copper Cable (ACC) – Part of the PLL CEI LR demo:  
This 3.5m , 30AWG cable assembly pre-configured to work in an LR link and designed to stretch the physical reach >3m. Total power consumption <2W.

OSFP800 and QSFP-DD800 – Part of the PLL CEI VSR, MR, LR demos:  
Pluggable IO standard supporting up to 800Gb/s in aggregate over an 8 x 112Gb/s electrical interface.

Amphenol Corporation is one of the world's largest designers and manufacturers of electrical, electronic and fiber optic connectors and interconnect systems, antennas, sensors and sensor-based products and coaxial and high-speed specialty cable.

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